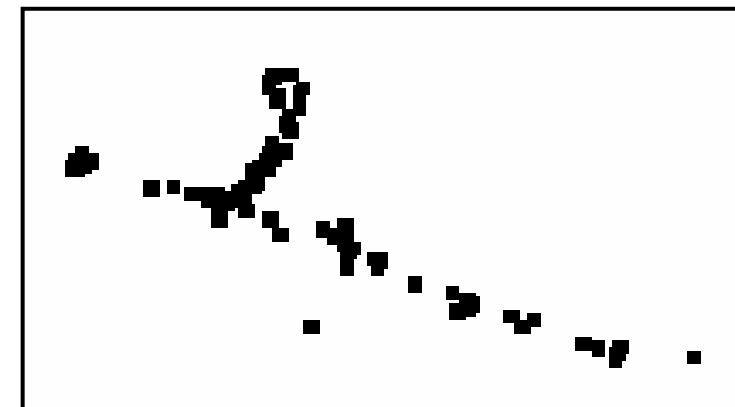


# Recent developments for digital TPC readout

Jan Timmermans - NIKHEF

- Micro Pattern Gas Detector: GridPix
- Integration of grid and readout: InGrid
- 3D readout: TimePix
- Discharge protection
- Future developments

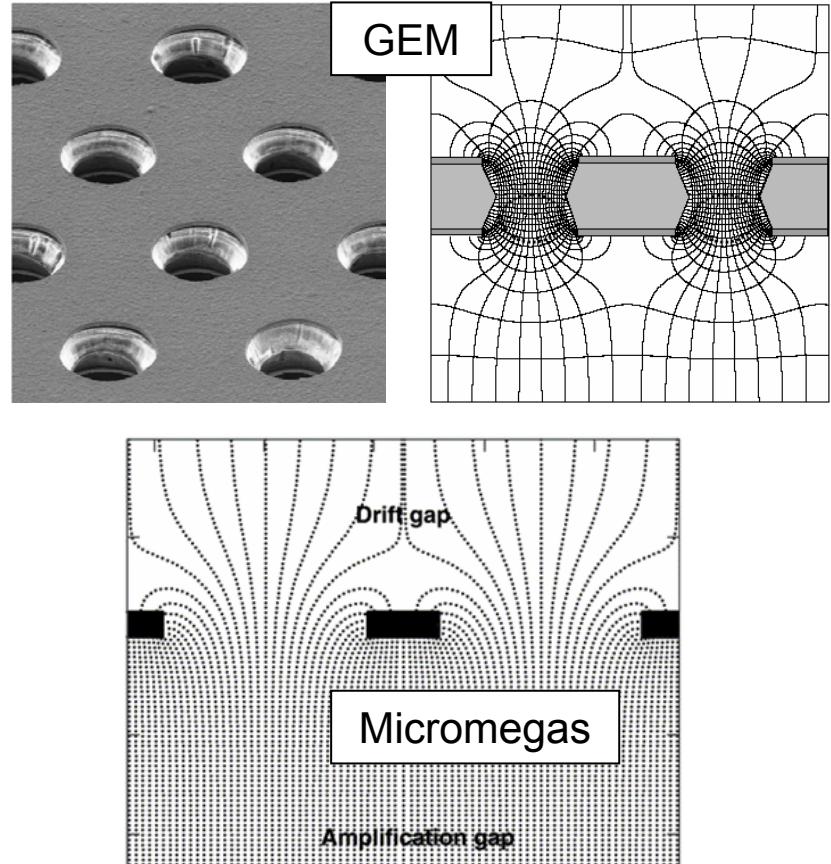
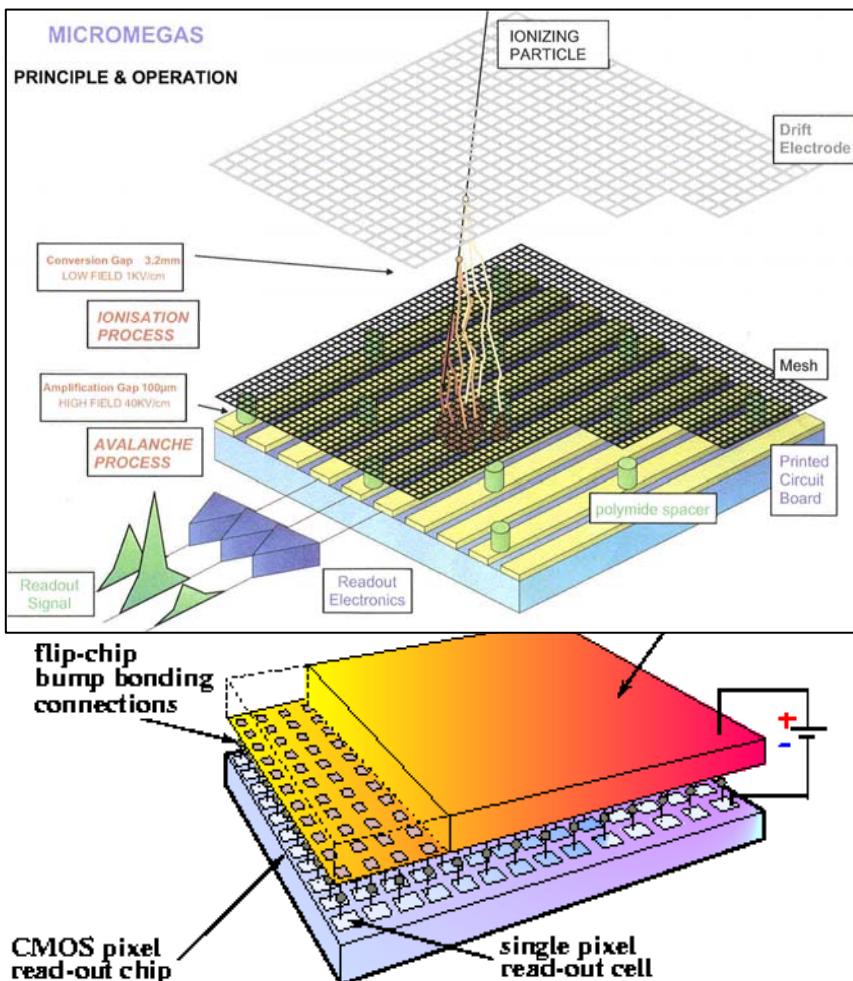


# Goals

- Gas multiplication GEM or Micromegas foil(s)
  - Charge collection with granularity matching primary ionisation cluster spread  
(this needs sufficiently low diffusion gas)
  - Investigate measurement  $dE/dx$  using cluster counting
- 
- 2D “proof of principle” based on existing Medipix2 readout chip: achieved
  - Add 3<sup>rd</sup> coordinate: Medipix2 → TimePix
  - Integrate grid with pixel chip: InGrid (new results)

# Micro Patterned Gaseous Detectors

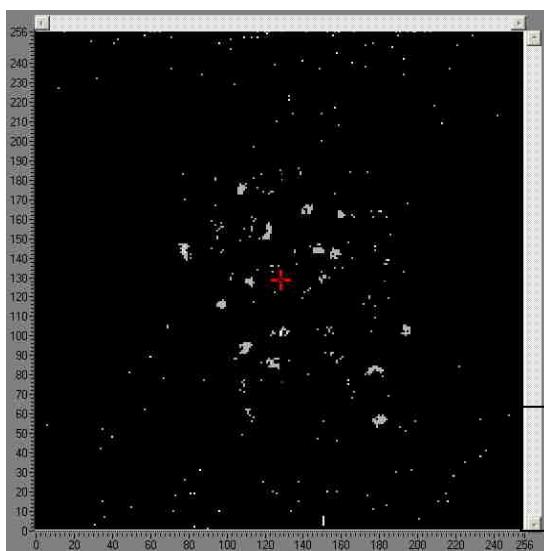
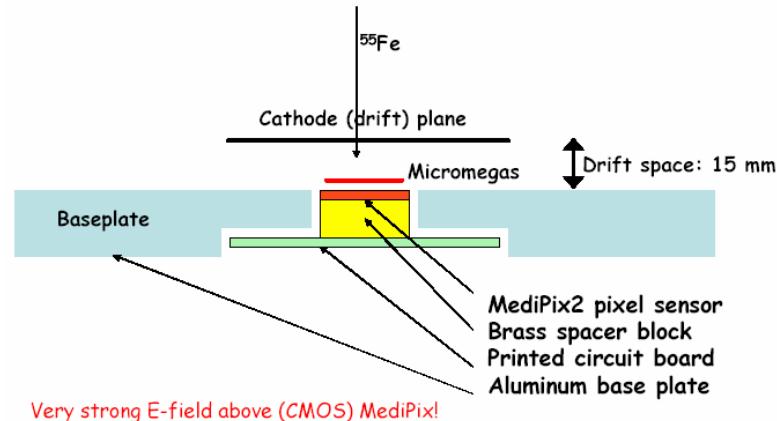
- High field created by Gas Gain Grids
- Most popular: GEM & Micromegas



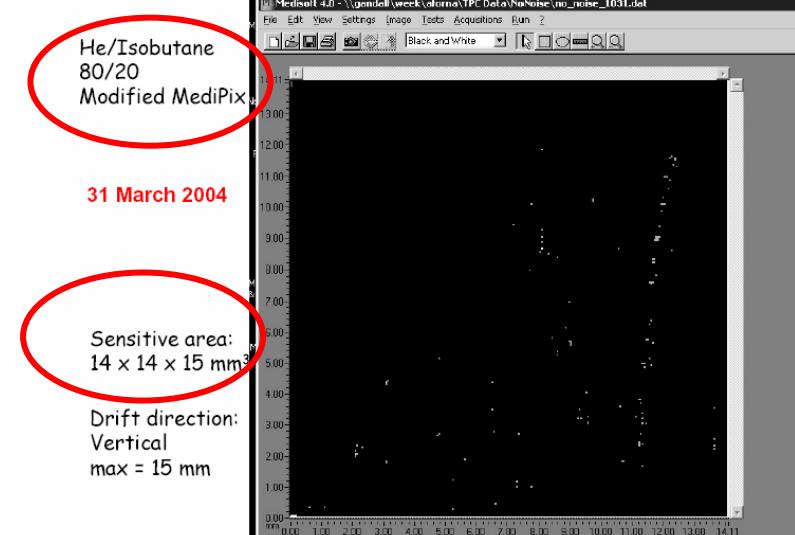
Use 'naked' CMOS pixel readout chip as anode

# Results pixel readout gas detectors

NIKHEF-Saclay-CERN-Twente



Ar/isobutane  
95/5



Observation of min. ionising cosmic muons: high spatial resolution +

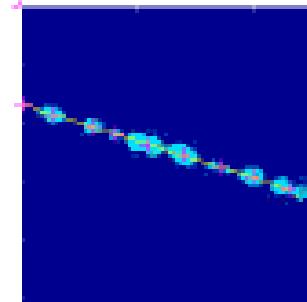
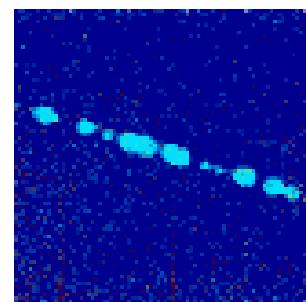
NIM A540 (2005) 295 (physics/0409048)

individual cluster counting !

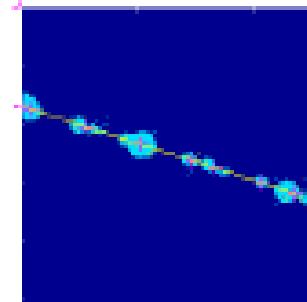
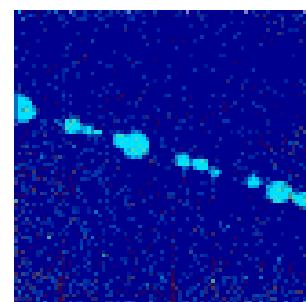


# Some events with fits ( $\beta$ source)

(from Freiburg GEM+Medipix setup - Andreas Bamberger)



Triple GEM  
Total gain ~60k



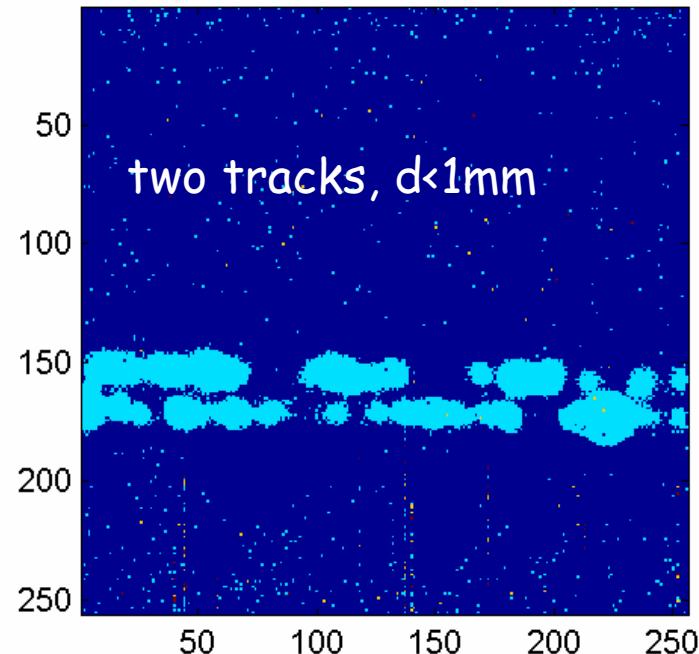
~ 50  $\mu\text{m}$  resolution

Difference between Micromegas and GEM setup  
understood (simulation Michael Hauschild/CERN)

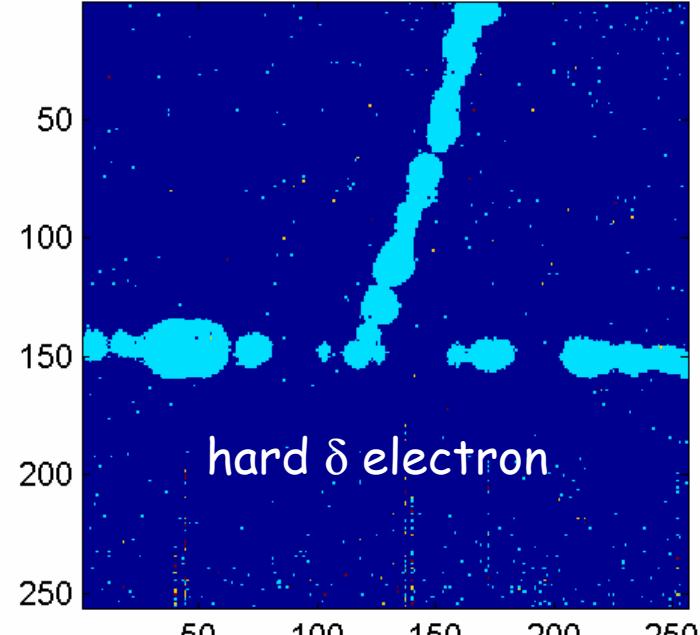
# 4. Testbeam at DESY: 3-GEM+Medipix

Freiburg  
Bonn

A28.09.2006\_16-07-17-156\_648ms.dat



B03.10.2006\_13-20-01-796\_348ms.dat



Lots of data to be analyzed

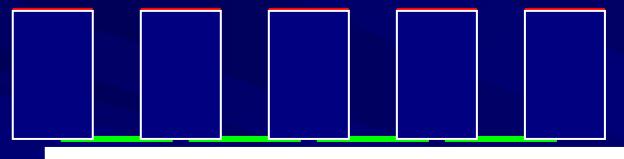
Still the same Medipix chip as 1.5 years ago

Prepare for Testbeam with Timepix in same setup a.s.a.p.

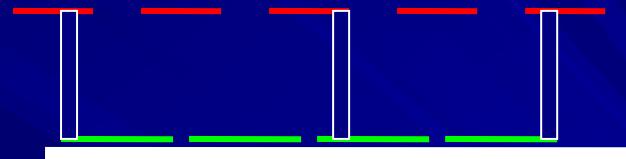
# InGrid

Integrate GEM/Micromegas and pixel sensor

‘GEM’

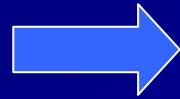
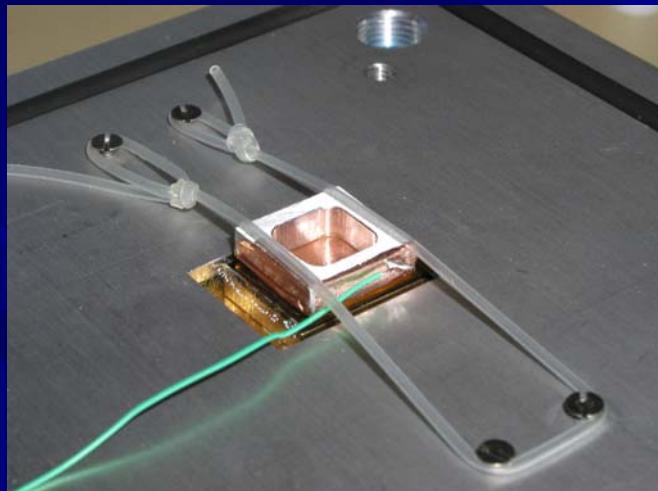


‘Micromegas’



By ‘wafer post processing’

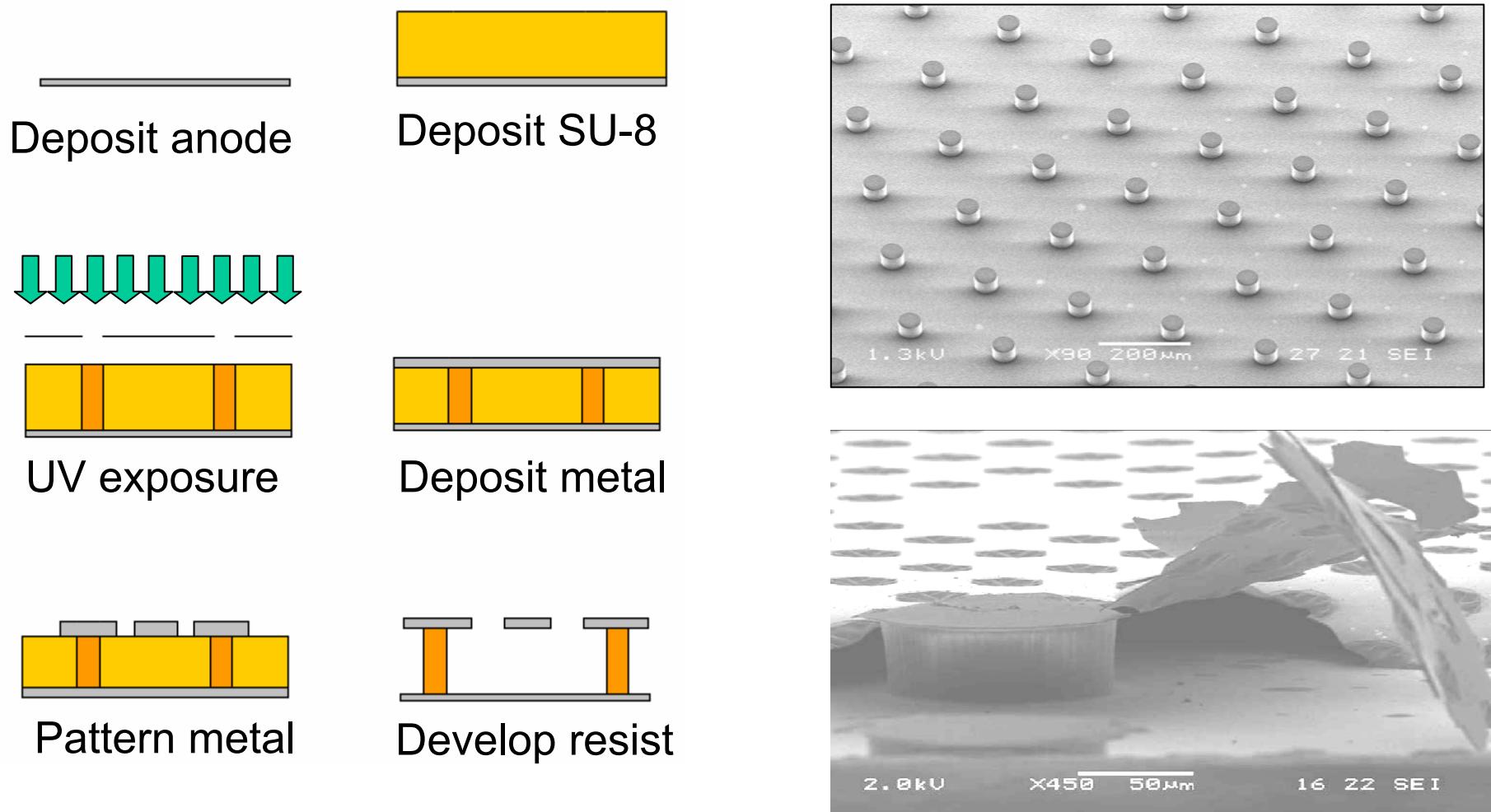
4” wafer



November 8, 2006

19 different fields of 15 mm Ø  
2 bonding pads / fields

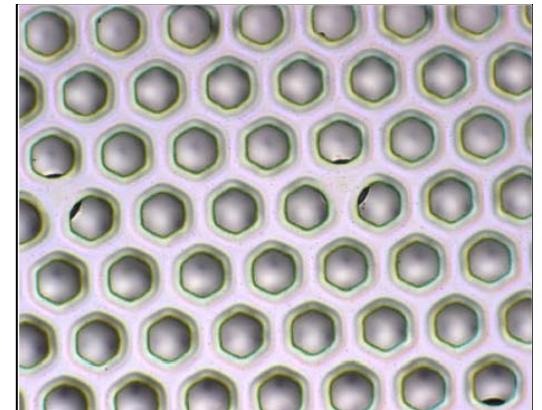
# NIKHEF/Twente: InGrid (Integrated Grid)



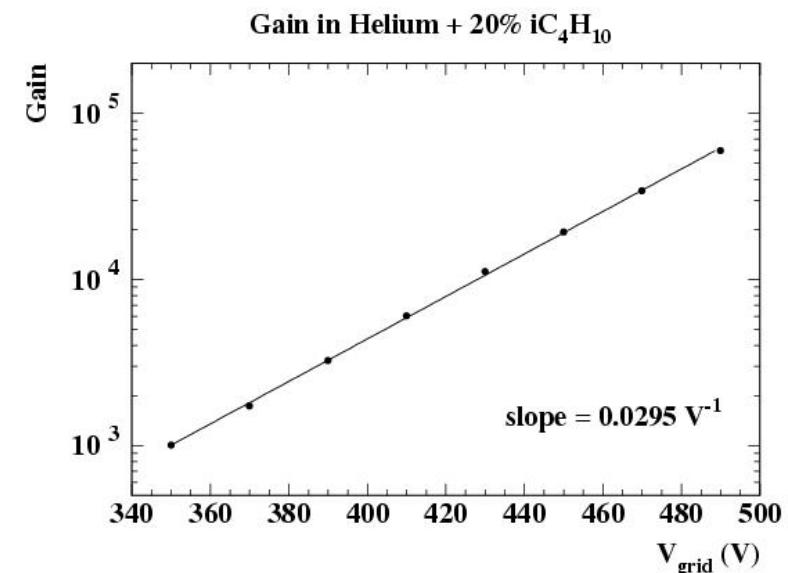
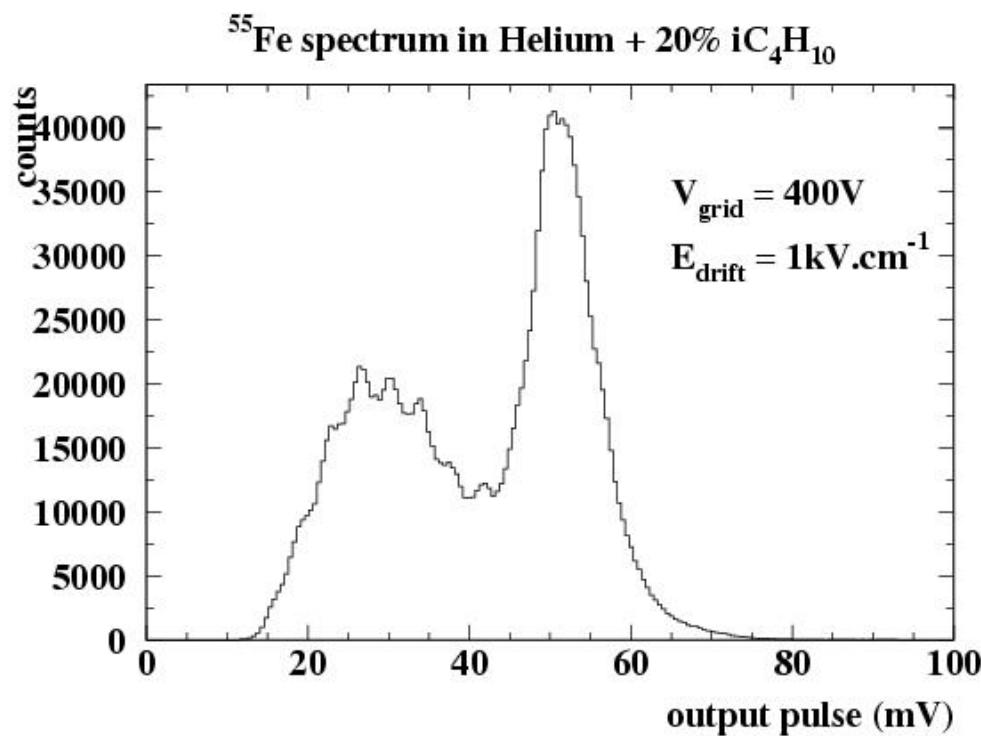
# Measuring the InGrid signals

( NIM A556 (2006) 490 )

(After 9 months of process tuning and unsuccessful trials)

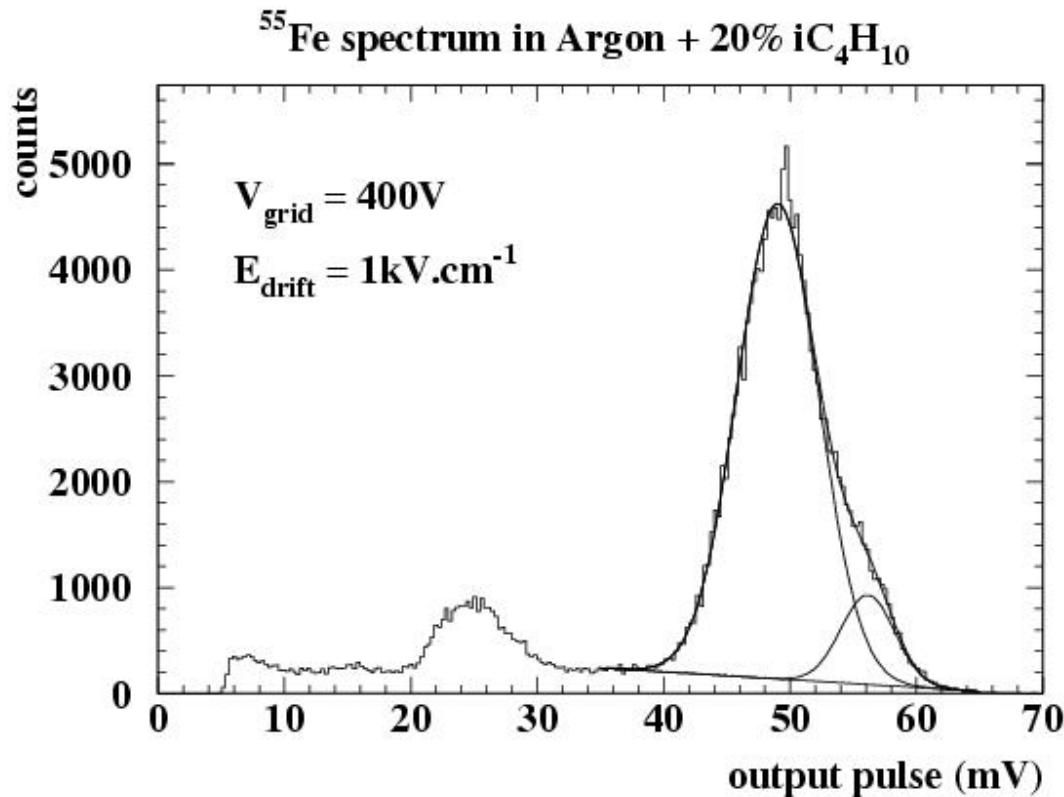


Pulseheight and gain: He + 20% iC<sub>4</sub>H<sub>10</sub>



• Gas gains  $10^3 - 6 \cdot 10^4$

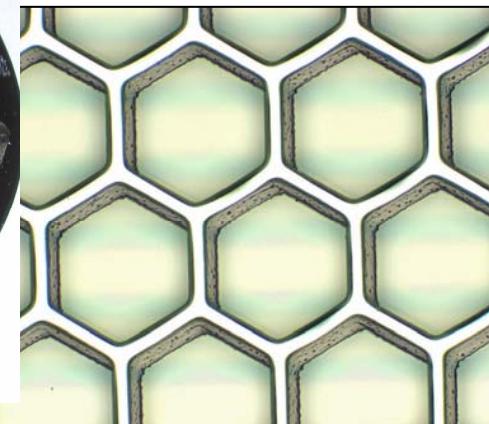
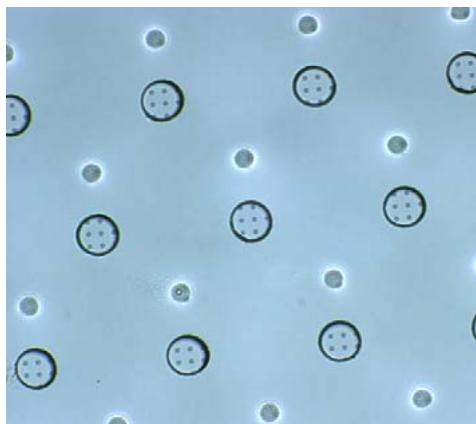
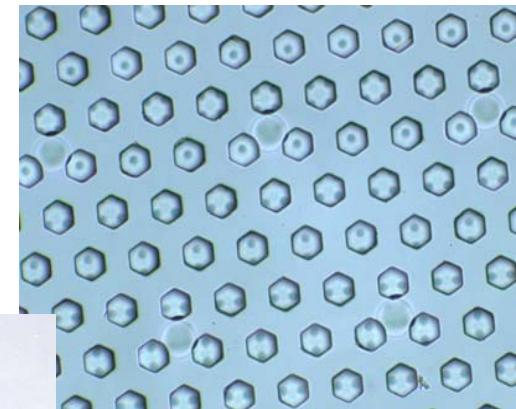
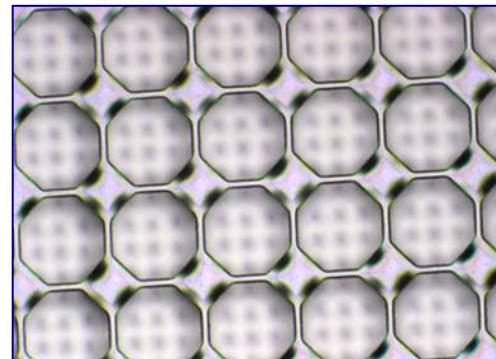
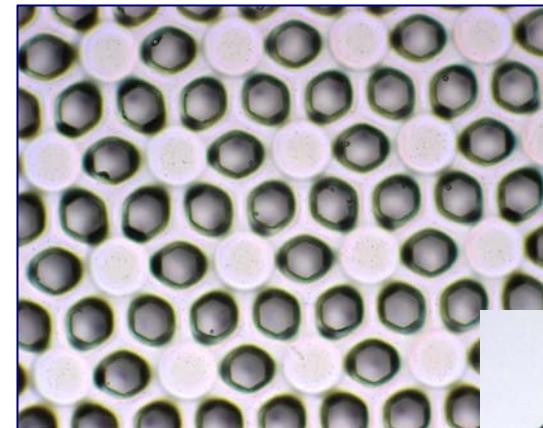
## Energy resolution in Argon IsoC<sub>4</sub>H<sub>10</sub> 80/20



- Observation of two lines:
  - $K_{\alpha}$  at 5.9 keV
  - $K_{\beta}$  at 6.4 keV
- Resolution  $\sigma_E/E = 6.5\%$   
(FWHM = 15.3%)
- Gain variations <  $\pm 5\%$

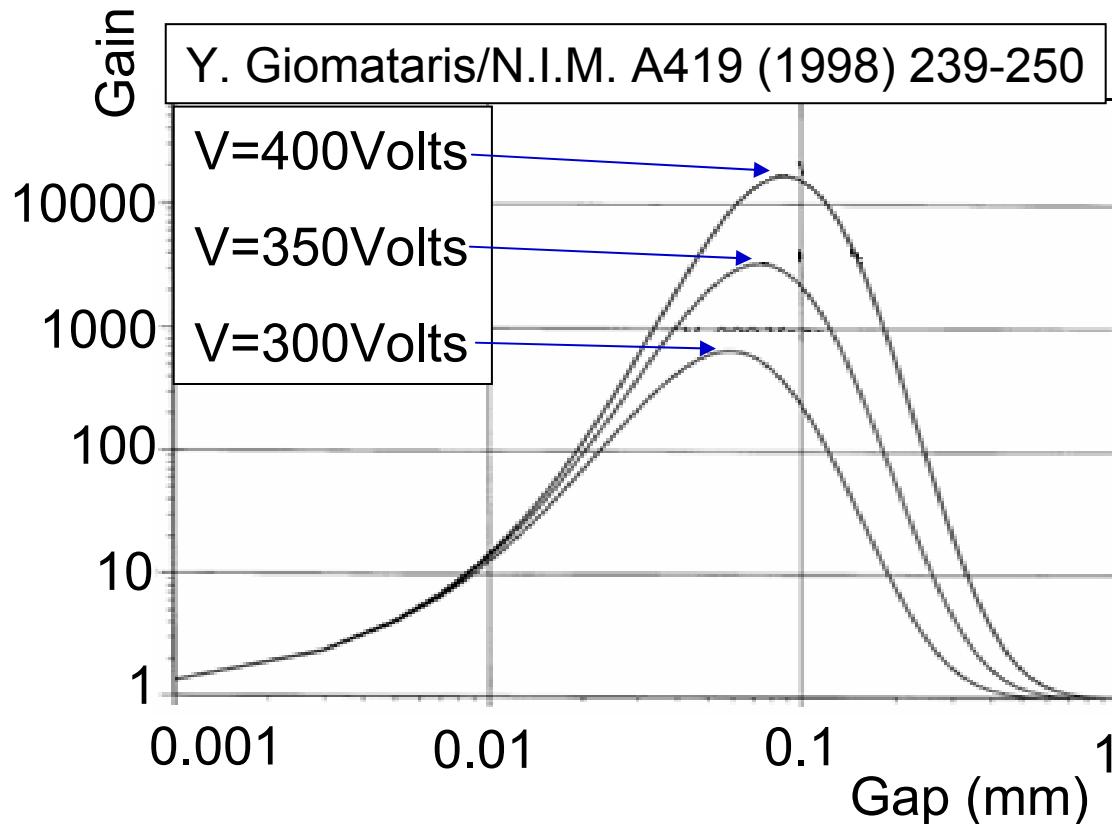
- Photo peak asymmetry seen
- Very good energy resolution

# Any field structure feasible



# Gain for different gap sizes

Maximum predicted in gain vs gap curve



$$M = e^{\alpha d}$$

$d$  gap thickness

$$\alpha = pAe^{-Bp/E}$$

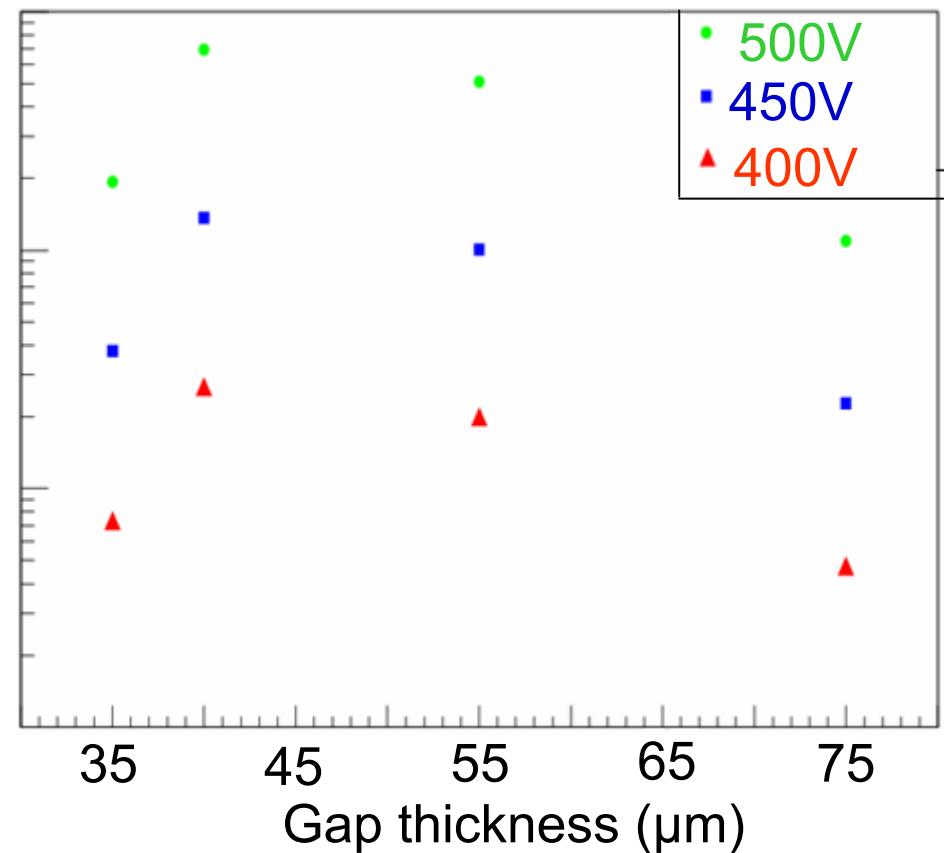
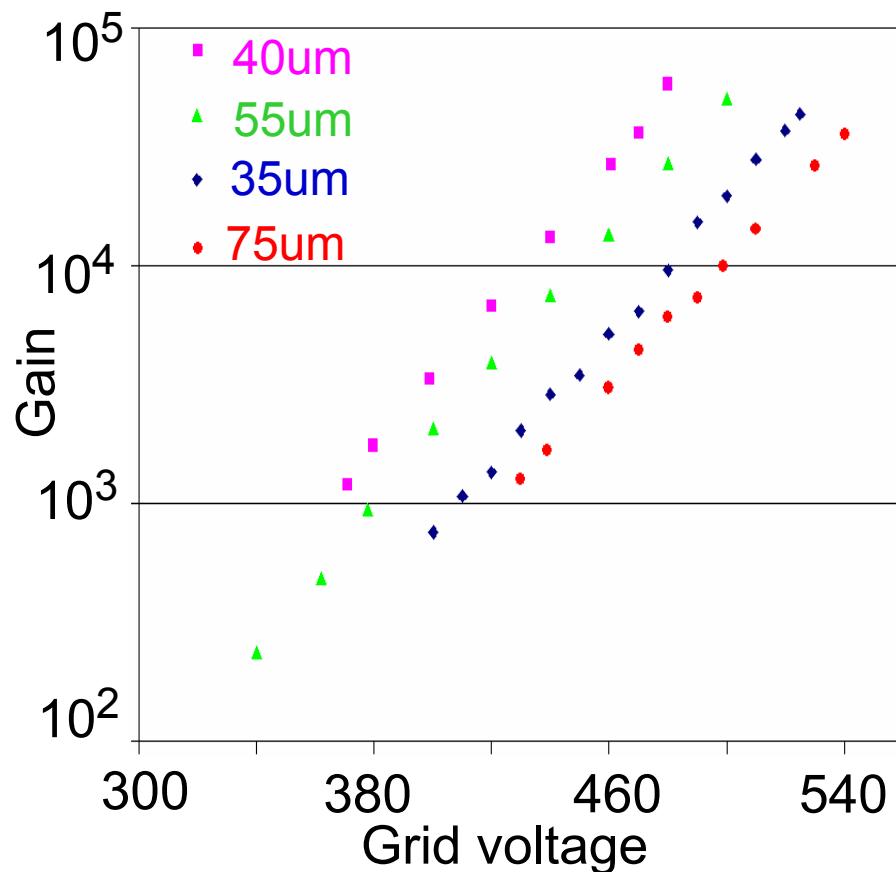
Rose & Korff

$p$  pressure

$A, B$  depend on gasmixture

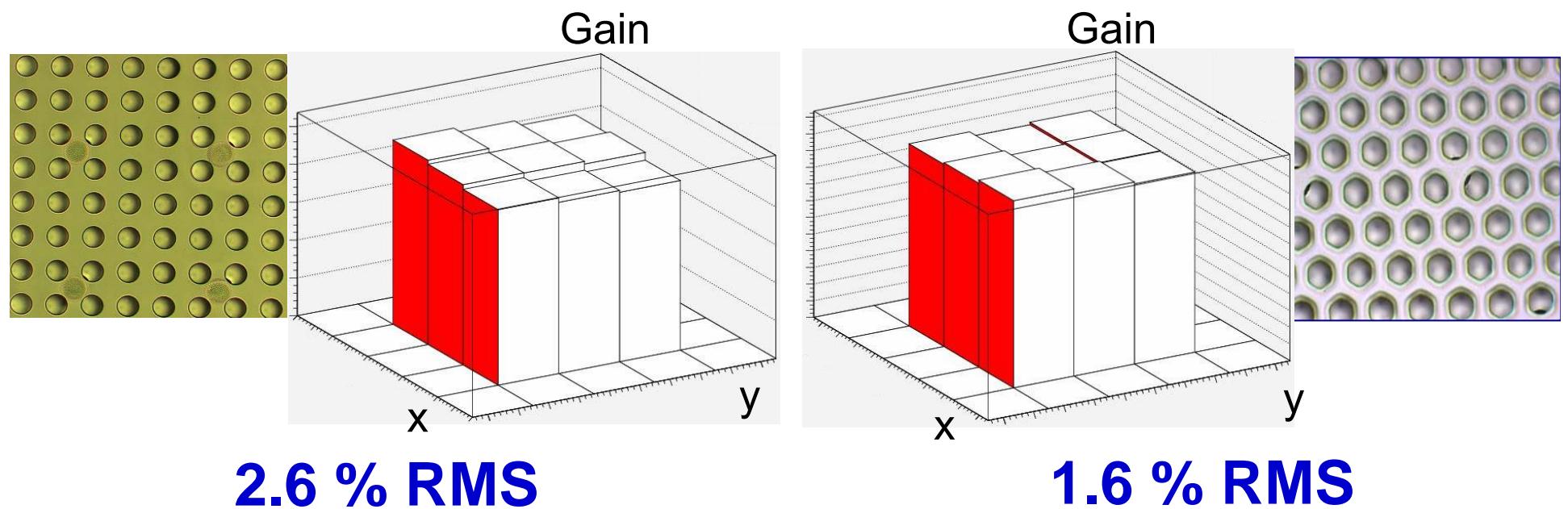
# Gain for different gap sizes

- But now we can make measurements



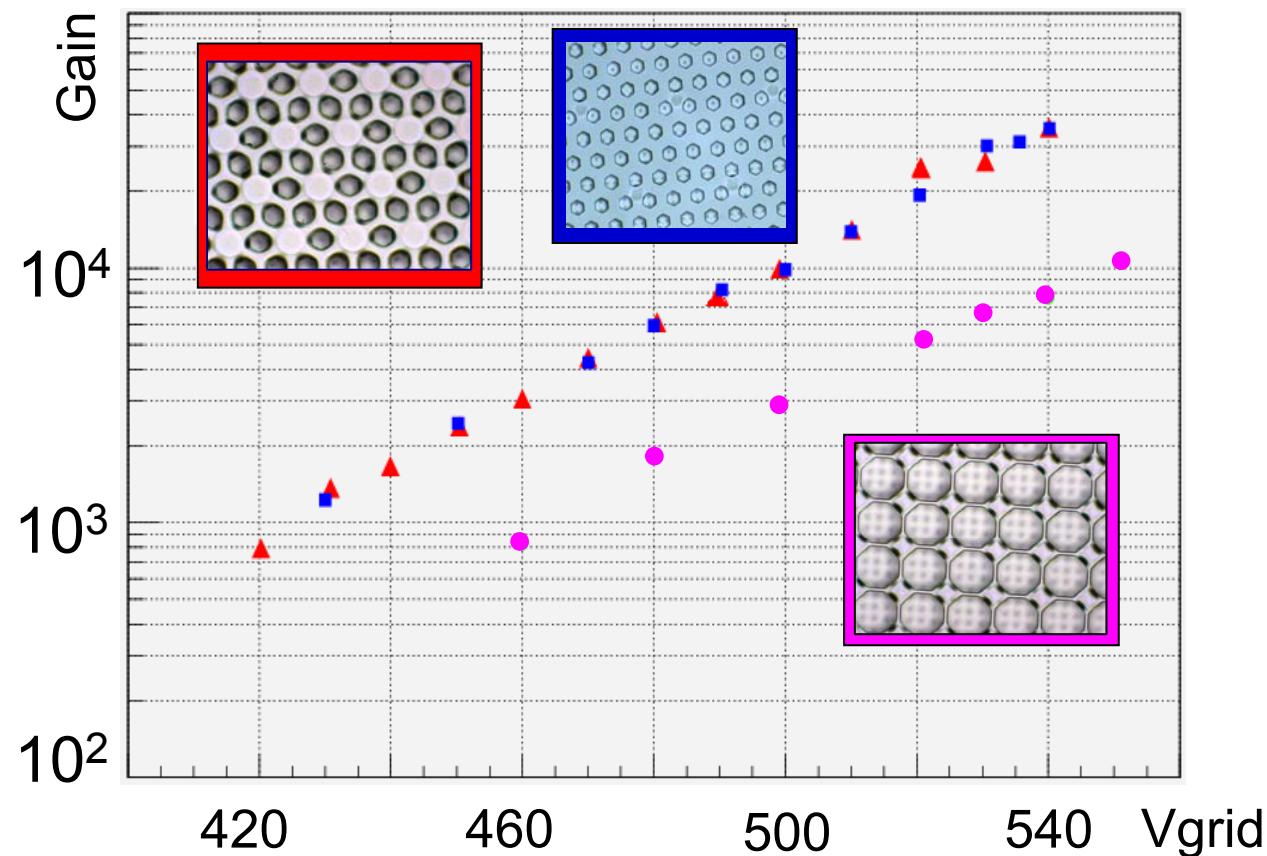
# Homogeneity

- Gain measurements scanning the surface of the detector
- Homogeneity given by grid quality



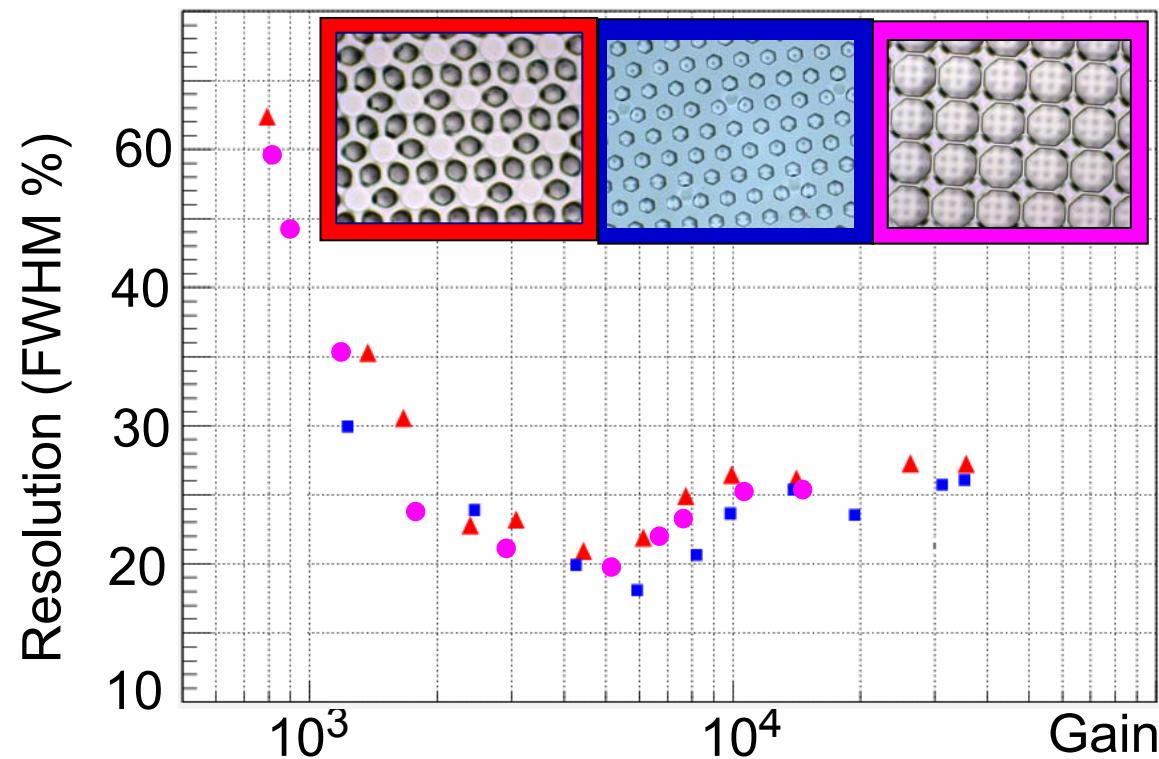
# Measured gain for different hole size

And measurements confirm simulations



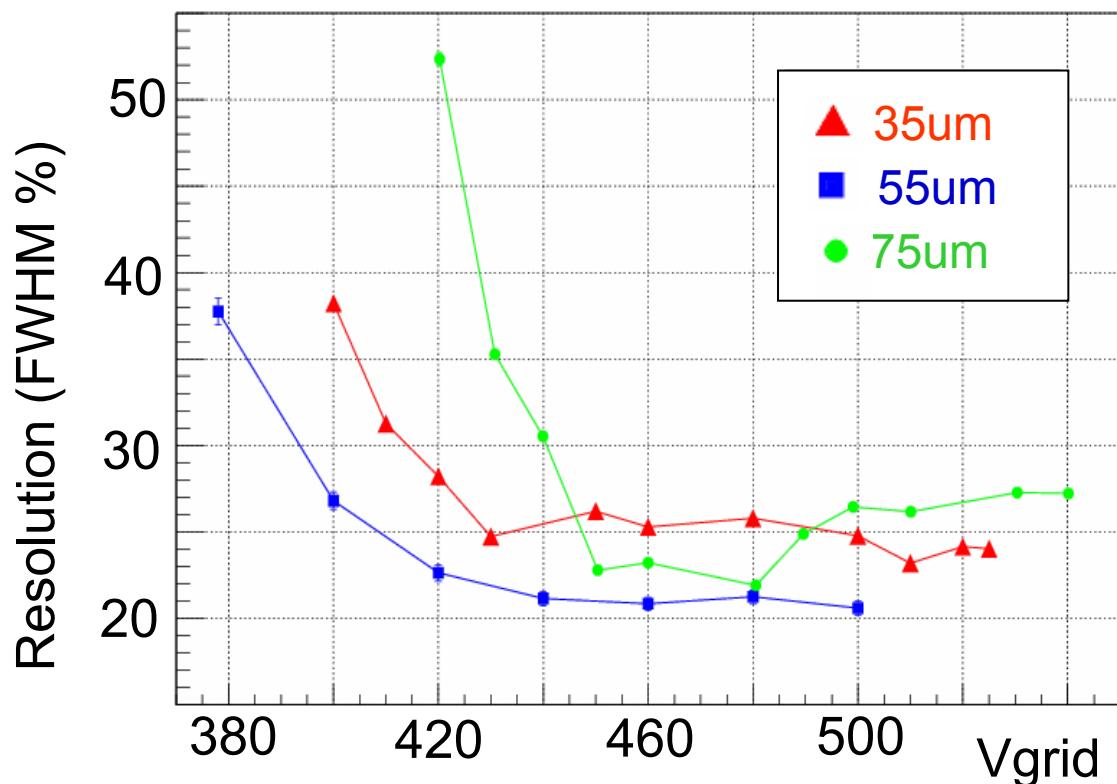
# Energy resolution

- Resolution depends on
  - Primary, attachment, T,P
  - Collection efficiency (field ratio)
  - Gain homogeneity & transverse diffusion

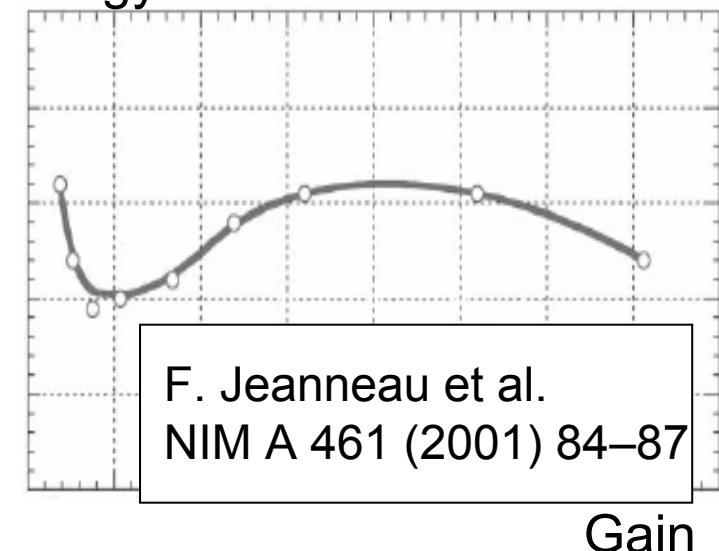


# Resolution as function of gap

- Why a parabolic behavior ?



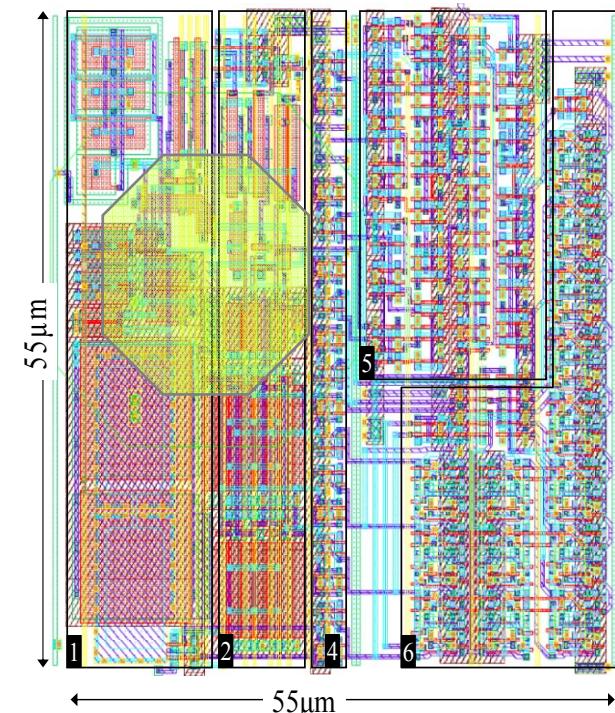
Energy resolution



# TimePix1 (EUDET: Freiburg, Saclay, CERN, NIKHEF)

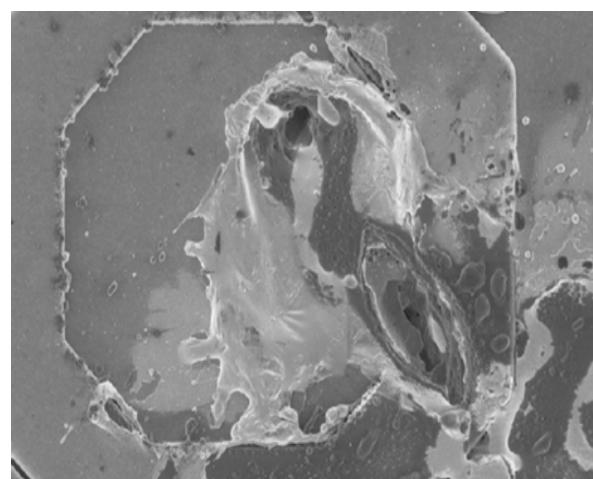
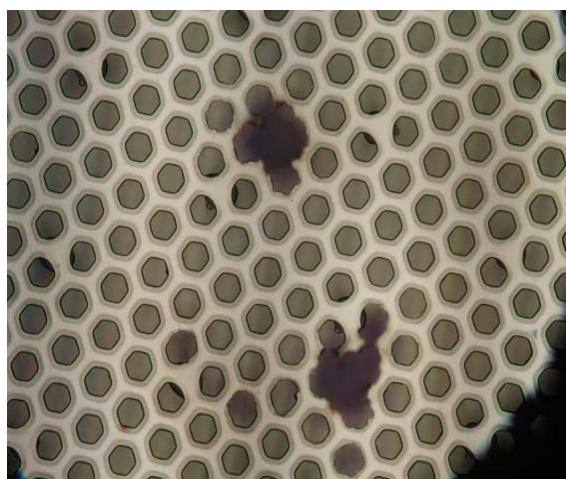


- Distribute clock to full 256x256 pixel matrix (50-100-160MHz)
- Enable counting by first hit after ‘shutter’ opens, until ‘shutter’ closes (common stop); also time-over-threshold possible
- Dynamic range  $2^{14} \times 10 \text{ ns} = 160 \mu\text{s}$
- (for the time being) no zero-suppress to remain fully compatible with Medipix2
- Shaping time ~200 ns
- Keep same chip-size, pixel-size, readout protocol
- 1st full reticle submit done July 2006;  
IT WORKS! Now preparing/doing tests in gas detectors.



# Sparking

- Chip faces 80kV/cm with no protection (unlike the GEM setup; 1.5 yr using same chip)
- Degradation of the field, or total destruction of grid but also CMOS chip



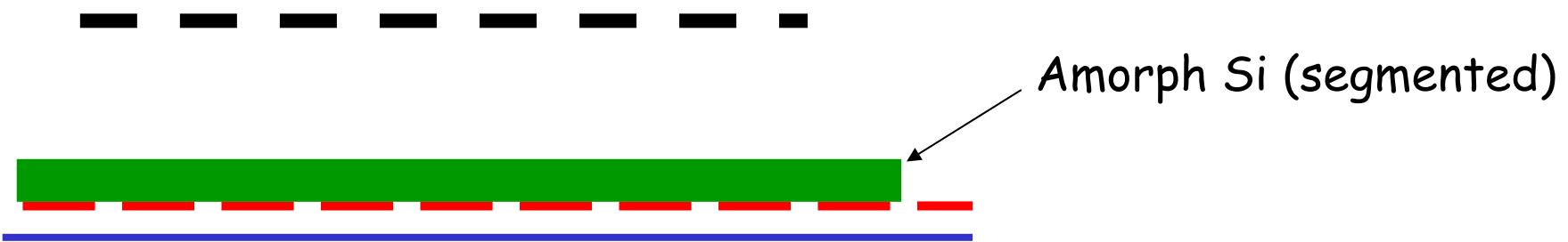
↔

10 $\mu$ m

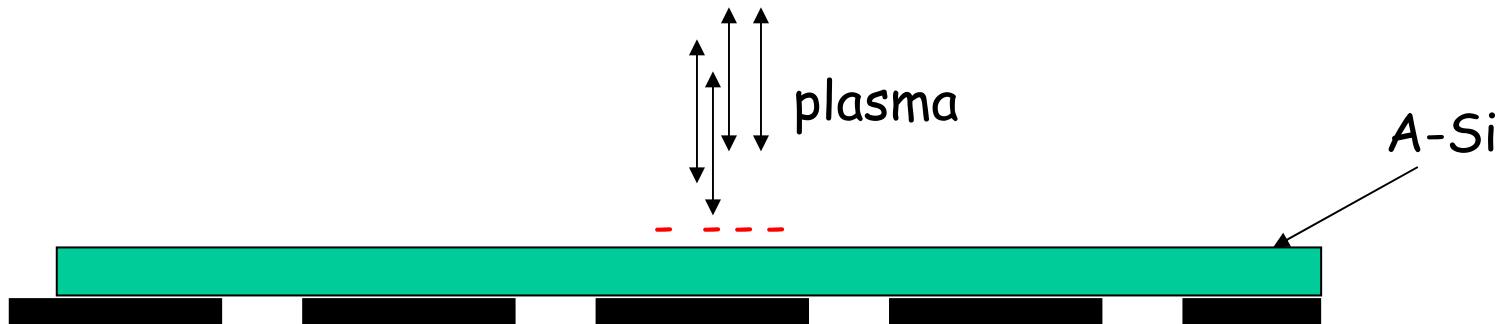
CMOS Chip protection against

- discharges
- sparks
- HV breakdowns
- too large signals

## Silicon Protection: SiProt



Empirical method:  
Try RPC technology



- RPC principle: reduction of local E-field
- Avalanche charge: electrostatic induction towards input pad
- Specific resistance:
  - high enough to 'block' avalanche charge
  - low enough to flow signal current
  - layer thickness  $4 \mu\text{m}$ ,  $R_{\text{vol}} = 0.2 G\Omega/\text{cm}$

## Technology

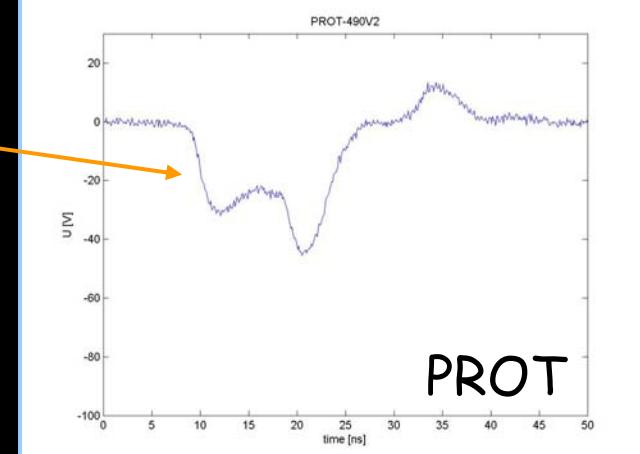
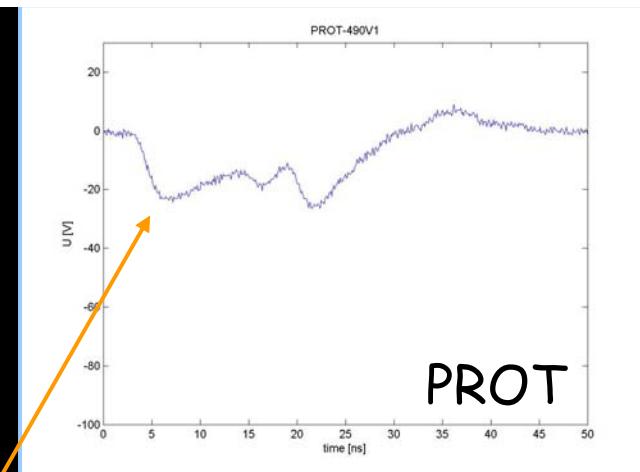
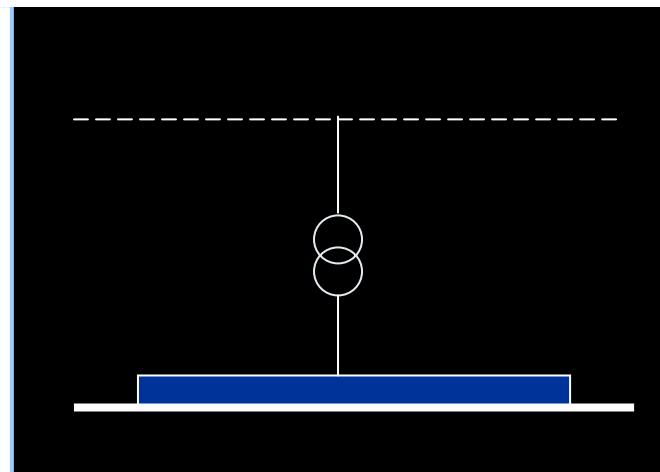
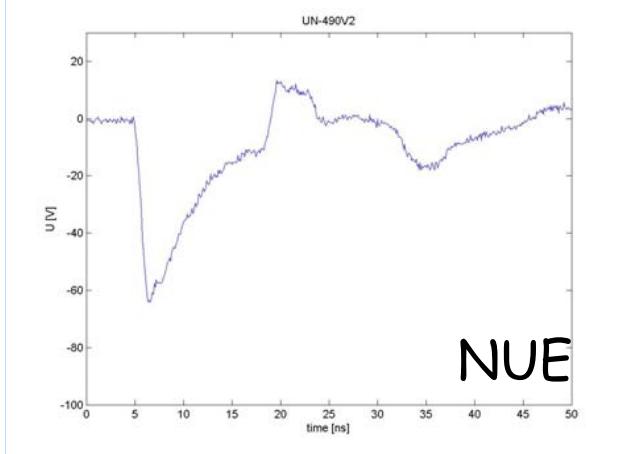
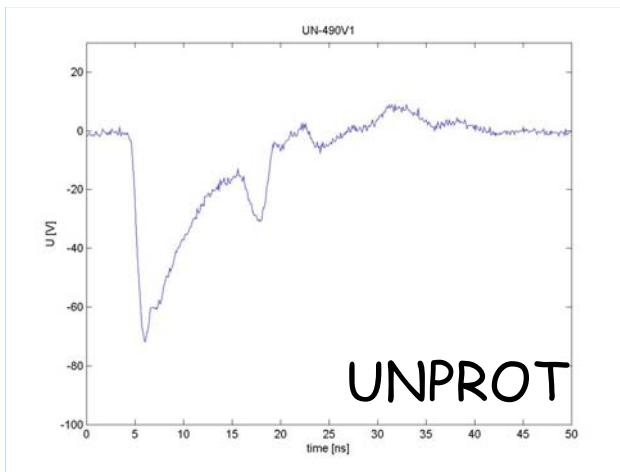
A-Si deposit possible in general; avoid wafers get too hot



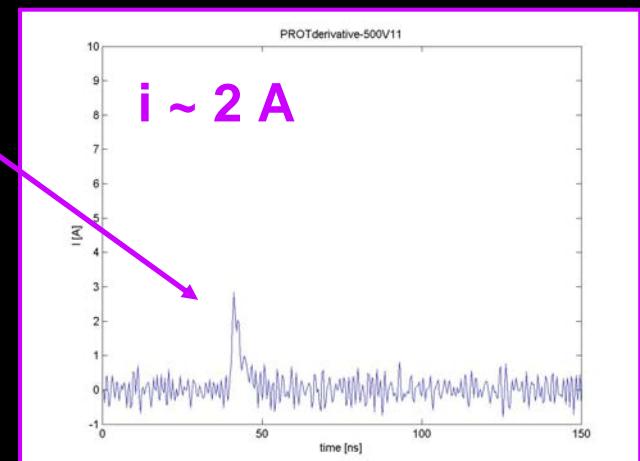
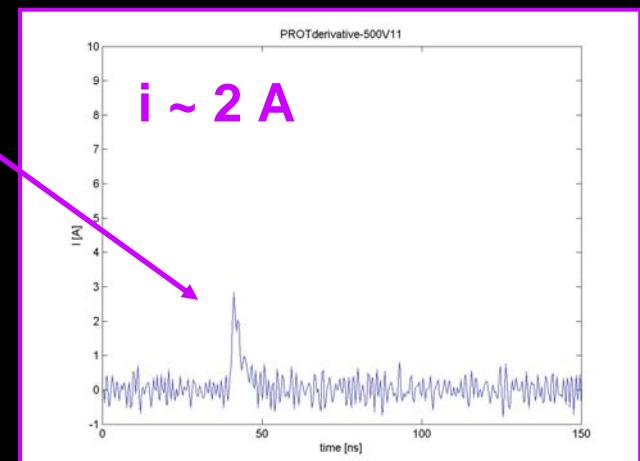
Univ. of Neuchatel/IMT/P. Jarron (CERN) uses this for integrated X-ray sensor/convertor on MediPix 2

Test: put Thorium in gas: Radon  $\alpha$ -decays:

- large (proportional) signals
- Discharges: like short circuits



**Slope less steep for protected anode**



**Current reduced**

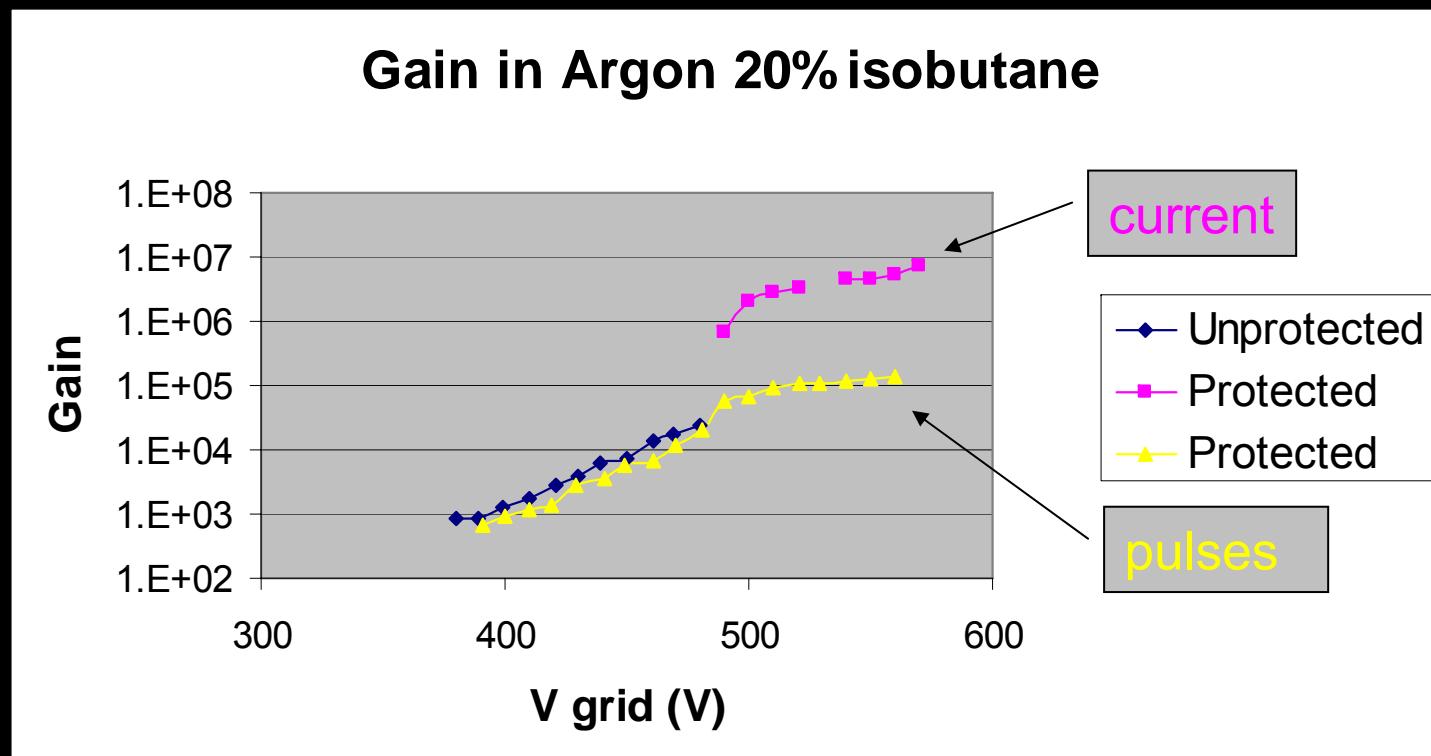
**Enough to protect  
the chip?**

Iron 55 source

Look at the pulses from a pre amplifier (low grid voltage)

Look at the current flowing through the power supply (high grid voltage)

Gain

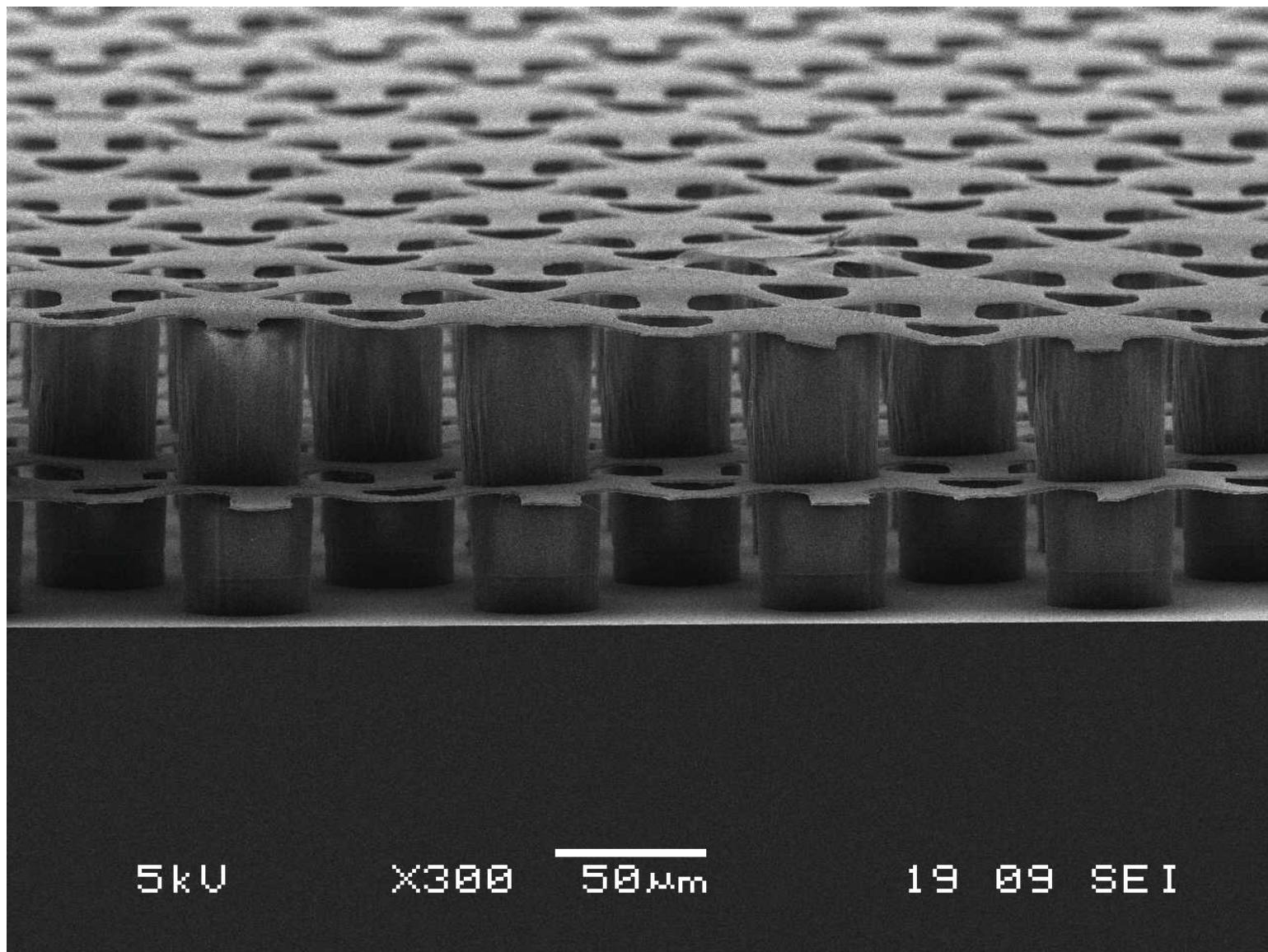


No sparks up to 570 V on the grid !

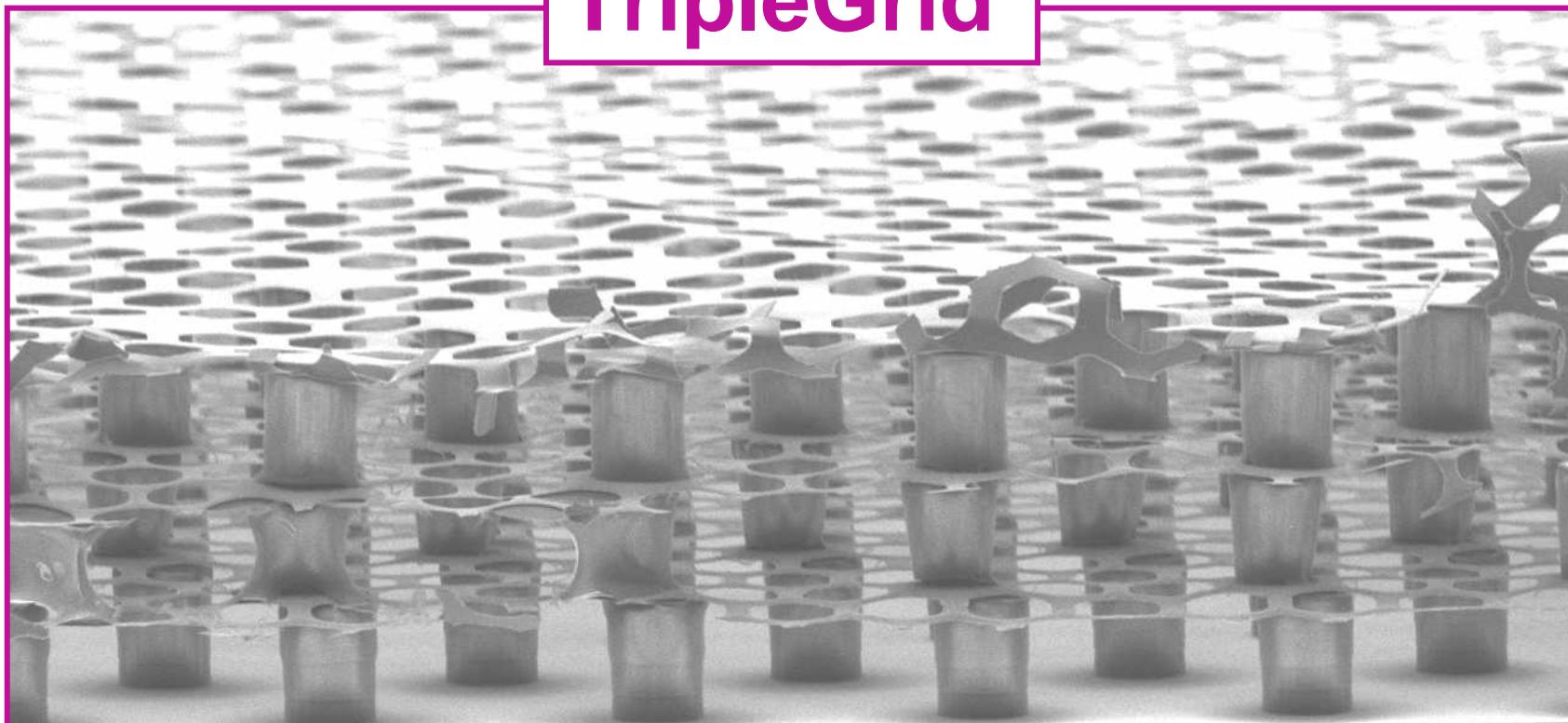
Burn the grid above 570...

Alternative:

TwinGrid



# TripleGrid



5kV

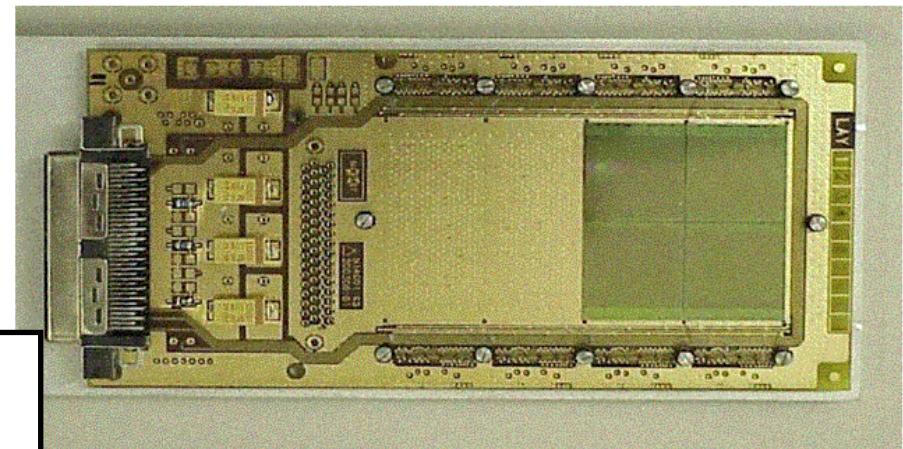
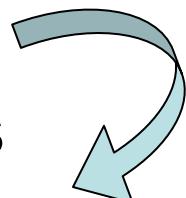
x230 100µm

17 18 SEI

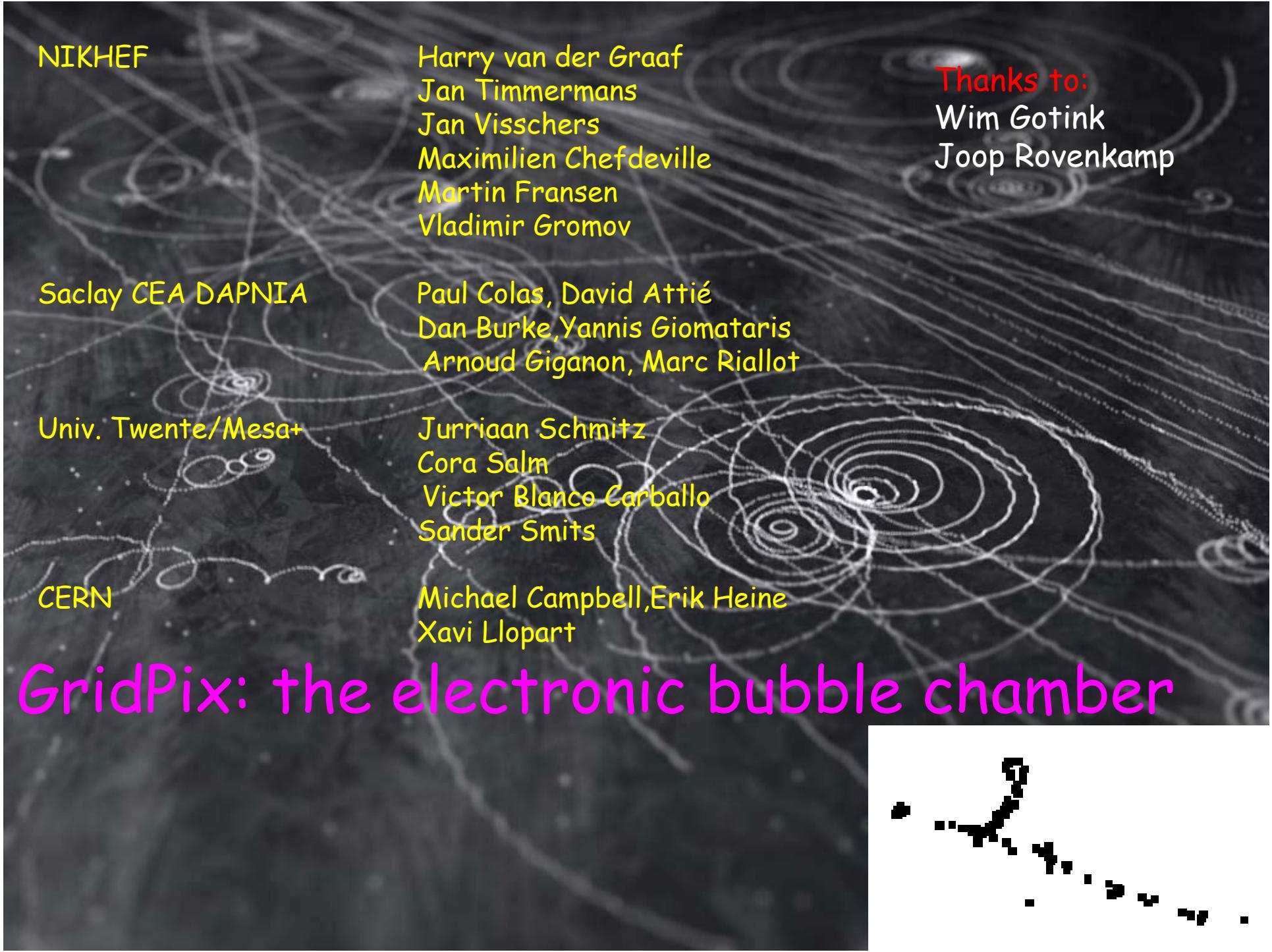
# Further Developments

RELAXD project (Dutch/Belgian)  
NIKHEF, Panalytical, IMEC, Canberra:

- Chip tiling: large(r) detector surfaces  
(2x2, 2x4 chips)
- Through Si connectivity: avoiding bonding wires
- Fast readout technology  
(~5 Gb/s)



- Octal chip board:  
56 mm x 110 mm  
12-layer pcb



NIKHEF

Harry van der Graaf  
Jan Timmermans  
Jan Visschers  
Maximilien Chefdeville  
Martin Fransen  
Vladimir Gromov

Saclay CEA DAPNIA

Paul Colas, David Attié  
Dan Burke, Yannis Giomataris  
Arnoud Giganon, Marc Riallot

Univ. Twente/Mesa+

Jurriaan Schmitz  
Cora Salm  
Victor Blanco Carballo  
Sander Smits

CERN

Michael Campbell, Erik Heine  
Xavi Llopert

Thanks to:  
Wim Gotink  
Joop Rovenkamp

# GridPix: the electronic bubble chamber

